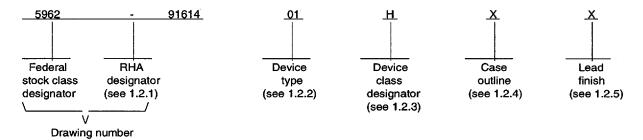
MICRO DR	ANDA OCIR AWIN WING IS A R USE BY A PARTMEN ENCIES C	CUITING VAILABLE ALL ITS DE THE	E	SHE PREP. Steve CHEC Gary 2	ARED L. Dund	BY PPROV	E 1 /AL DAT	E 2	3		ROCIF	RCUIT ., DC/[, HYB	RID, L	, OHIO	7. 432	VOLT	E 12	L	14
SHEET REV STATE OF SHEET PMIC N/A STA MICRO DR THIS DRAW FOR	ANDA OCIR AWIN WING IS A	CUI" IG VAILABL ALL		SHE PREP. Steve CHEC Gary Z	ARED L. Dunc EKED B Zahn	BY				4 MICI	5	6 DEFEI	7 NSE S	8 UPPL MBUS	9 Y CEI	10 NTER 0 432	11 COLU 16-500	12 IMBUS	13	
SHEET REV STATE OF SHEET PMIC N/A STA MICRO	ANDA OCIR	CUI	Г	SHE PREP Steve	ARED L. Dune	can				E 4	5	6 DEFEI	7 NSE S	8 UPPL	9 Y CEI	10	11 COLU	12	13	
SHEET REV STATI OF SHEET				SHE	ET					E 4	5	6 DEFEI	7 NSE S	8 UPPL	9 Y CEI	10	11 COLU	12	13	
SHEET REV STATE										E 4							<u> </u>	 		
SHEET	SHEETS					Ε	E	E	E	E	E	E	E	E	E	E,	E			
			\longrightarrow	ı		!	l			L	l '	1								
	:																			
SHEET																				
REV		 			17															
E	type for V subg p and sepa	Table I; Changed the min and max limits for Radhard levels L,R device type 02 for the following tests +V _{OUT} , -V _{OUT} . Changed the max limits for VR _{LINE} , VR _{LOAD} , I _{IN} , and Eff. For the I _{RIP} test separate subgroups 1,2,3 to subgroup 1 for device type 01 max limit of 60 mApp and for subgroups 2 and 3 the max limit of 100 mA. For the I _{RIP} test separate subgroups 1,2,3 to subgroup 1 for device type 02 max limit of 80 mAp-p and for subgroup 2 and 3 the max limit of 120 mAp-p.									02-03		¥.	K.A.	Cotto	ngim				
				and Cla		device	es. Ad	ded R	adHar	rd requ	iremeı	nts.	97-10-29				K.A. Cottongim			
D					DI	ESCR	IPTIO	N					DA	TE (Y	R-MO-E)A)	APPROVED			
LTR D	1								EVISI	ONS										

DESC FORM 2233
APR 97
DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

5962-E189-98

- 1.1 <u>Scope</u>. This drawing documents five product assurance classes, class D (lowest reliability), class E, (exceptions), class G (lowest high reliability), class H (high reliability), and class K, (highest reliability) and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of radiation hardness assurance levels are reflected in the PIN.
 - 1.2 PIN. The PIN shall be as shown in the following example:



- 1.2.1 <u>Radiation hardness assurance (RHA) designator</u>. Device classes H and K RHA marked devices shall meet the MIL-PRF-38534 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device. Only, the RHA levels specified herein are available.
 - 1.2.2 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Device type	Generic number	Circuit function				
01	MHF+2815D/883,MHF+2815DF/883	DC-DC converter, 15 W, ±15 V output				
02	SMHF+2815D,SMHF+2815DF	DC-DC converter, 15 W, ±15 V output				

1.2.3 <u>Device class designator</u>. This device class designator shall be a single letter identifying the product assurance level as follows:

Device class

Device performance documentation

D, E, G, H, or K

Certification and qualification to MIL-PRF-38534

1.2.4 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style		
X	See figure 1	8	Dual-in-line		
Z	See figure 1	8	Flange package		

1.2.5 Lead finish. The lead finish shall be as specified in MIL-PRF-38534.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-91614
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL E	SHEET 2

	-							
1.3 Absolute maximum ratings. 1/								
Input voltage range Power dissipation (PD) Output power Lead soldering temperature (10 seconds) Storage temperature range	6 W 15.34 W +300°C							
1.4 Recommended operating conditions.								
Input voltage range								
2. APPLICABLE DOCUMENTS								
2.1 Government specification, standards, and handbook. The this drawing to the extent specified herein. Unless otherwise specisure of the Department of Defense Index of Specifications and Solitation.	ecified, the issues	of these documents are the	se listed in the					
SPECIFICATION								
DEPARTMENT OF DEFENSE								
MIL-PRF-38534 - Hybrid Microcircuits, General Specification for.								
STANDARDS								
DEPARTMENT OF DEFENSE								
MIL-STD-883 - Test Methods and Procedures for Mic MIL-STD-973 - Configuration Management. MIL-STD-1835 - Microcircuit Case Outlines.	roelectronics.							
HANDBOOK								
DEPARTMENT OF DEFENSE								
MIL-HDBK-780 - Standard Microcircuit Drawings.								
(Unless otherwise indicated, copies of the specification, stand Document Order Desk, 700 Robbins Avenue, Building 4D, Philad			andardization					
2.2 <u>Order of precedence</u> . In the event of a conflict between the this drawing takes precedence. Nothing in this document, howe specific exemption has been obtained.								
1/ Stresses above the absolute maximum rating may cause pe maximum levels may degrade performance and affect reliab		o the device. Extended op	eration at the					
STANDARD	SIZE		5062-01614					

MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS

COLUMBUS, OHIO 43216-5000

Α

REVISION LEVEL

Ε

5962-91614

3

SHEET

3. REQUIREMENTS

- 3.1 Item requirements. The individual item performance requirements for device classes D, E, G, H, and K shall be in accordance with MIL-PRF-38534. Compliance with MIL-PRF-38534 may include the performance of all tests herein or as designated in the device manufacturer's Quality Management (QM) plan or as designated for the applicable device class. Therefore, the tests and inspections herein may not be performed for the applicable device class (see MIL-PRF-38534). Futhermore, the manufacturers may take exceptions or use alternate methods to the tests and inspections herein and not perform them. However, the performance requirements as defined in MIL-PRF-38534 shall be met for the applicable device class.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking of Device(s)</u>. Marking of device(s) shall be in accordance with MIL-PRF-38534. The device shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's vendor similar PIN may also be marked as listed in QML-38534.
- 3.6 <u>Data</u>. In addition to the general performance requirements of MIL-PRF-38534, the manufacturer of the device described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, for each device type listed herein. Also, the data should include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DSCC-VA) upon request.
- 3.7 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance (original copy) submitted to DSCC-VA shall affirm that the manufacturer's product meets the performance requirements of MIL-PRF-38534 and herein.
- 3.8 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.

4. QUALITY ASSURANCE PROVISIONS

4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

STANDARD
MICROCIRCUIT DRAWING
DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43216-5000

SIZE A		5962-91614
·	REVISION LEVEL E	SHEET 4

		TABLE I. <u>Ele</u>	ectrical performance	ce characteristic	S.		-	
Test	Symbol	-55°C ≤ T	tions <u>1</u> / C ≤+125°C Ic ±5 percent,	Group A subgroups	Device Type	Lii	Unit	
		no external	sync, $C_L = 0$, wise specified			Min	Max	
Output voltage	+V _{OUT}	V _{IN} = 16, 28, and 40 V dc,		1	01,02	14.85	15.15	v
				2,3	01,02	14.70	15.30	
			L,R	1,2,3	02	14.25	15.75	
	-V _{OUT}			1	01,02	-14.78	-15.23	
				2,3	01,02	-14.63	-15.38	
			L,R	1,2,3	02	-14.18	-15.82	
Output current 2/	lout	V _{IN} = 16, 28, an	d 40 V dc	1,2,3	01	0.0	0.900	Α
					02	0.0	0.700	
			L,R	1,2,3	02	0.0	0.700	
Output ripple 3/ voltage	V _{RIP}	l _{OUT} = ±.500 A, B.W. = 10 kHz to	o 2MHz	1,2	01		80	mV p-p
vollago		DIVI = 10 III IZ II	5 Z.W. 12		02		175	_
				3	01		120	
					02		275	
			L,R	1,2,3	02		350	
Line regulation +V _{OUT}	VRLINE	I _{OUT} = ±.500 A, V _{IN} = 16 and 40	V dc	1,2,3	01,02		50	mV
			L,R	1,2,3	02		100	
-V _{OUT}				1,2,3	01,02		100	mV
			L,R	1,2,3	02		200	
Load regulation +VOUT	VR _{LOAD}	$I_{OUT} = 0$ to ±.50	00 A,	1,2,3	01,02		50	mV
			L,R	1,2,3	02		100	
- ^V o∪T				1,2,3	01		100	
					02		150	
			L,R	1,2,3	02	L	300	

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-91614
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		E	5

Test	Symbol	-55	Conditions °C ≤ T _C ≤	≤+125°C		Group A subgrou		Device Type	Limi	ts	Unit
		no exte	28V dc ±5 ernal sync otherwise	c, C _I = (),				Min	Max	
Cross regulation 4/ (-V _{OUT} only:)	X _{REG}	50% I _{OUT} = 0.500 A, +I _{OUT} = 50% to 10%, -I _{OUT} = 50% 50% I _{OUT} = 0.500 A, -I _{OUT} = 50% to 10%, +I _{OUT} = 50%				1		01		6	%
									6		
		50% I _{OUT} = .500 A, +I _{OUT} = 70% to 30%, -I _{OUT} = 30% to 70%			1		02		6		
				L,R						10	
Input current	Ι _Ν	I _{OUT} = 0,	inhibit pi <u>n</u>	(pin 1) :	= 0	1,2,3		01,02		12	mA
				L,R				02		15	
		I _{OUT} = 0,	inhibit pin	(pin 1) :	= open			01,02		50	
				L,R				02		100	
Input ripple current	IRIP	OUT = ±.5	500 A,			1		01		60	mA p-p
		I _{OUT} = ±.500 A, B. W. = 10 kHz to 10 MHz				2,3		01		100	
						1		02		80	
			_			2,3		02		120	
				L,R		1,2,3		02		150	
Efficiency	Eff	I _{OUT} = ±.5	600 A			1		01,02	76		%
			_			2,3		01,02	74		
				L,R		1,2,3		02	70		
Isolation	ISO	500 V dc	_	input to	output	1		01,02	100		МΩ
				L,R				02	100		
				input to	case			01,02	100		
				L,R				02	100		
				output t	o case			01,02	100		
				L,R				02	100		
See footnotes at end	l of table.										
MIC	STANDA ROCIRCUIT			•		ZE A				596	2-91614
DEFENSE S COLU				REVIS	SION LEV	ÆL .	SHEE	r 6			

Test	Symbol		ditions 1/	Group A subgroups	Device	Lin	nits	Unit	
•		V _{IN} = 28V o	-55°C ≤ T _C ≤+125°C V _{IN} = 28V dc ±5 percent, no external sync, C _L = 0, unless otherwise specified		Туре	Min Max			
Internal power	PD	PIN - POUT		1,2,3	01,02		6	w	
dissipation, short circuit		L,R			02		8.5		
Switching frequency	witching frequency F _S		I _{OUT} = ±.500 A		01,02	500	600	kHz	
				5,6	01,02	480	620		
			L,R	4,5,6	02	400	700		
Sync range 5/	4,5,6 01,02 50		500	600	kHz				
			L,R		02	500	600	:	
Output response to step transient load changes 6/+VOUT	VO _{TLOAD}	+I _{OUT} = .2 .500 A, -I _{OU}	+I _{OUT} = .250 A to/from .500 A, -I _{OUT} = .500 A		01,02	-600	+600	mV pk	
			L,R		02	-1200	+1200		
-Vout		-l _{OUT} = .25 .500 A, +l _O	50 A to/from UT = .500 A	4,5,6	01,02	-600	+600		
			L,R		02	-1200	+1200		
Recovery time, step	TT _{LOAD}	+l _{OUT} = .2	50 A to .500 A,	4,5,6	01		200	·μs	
transient load changes 6/ 7/		-lout = .5	00 A		02		600		
+V _{OUT}			L,R		02		1200		
+V _{OUT}		+l _{OUT} = .5	00 A to .250 A,	4,5,6	01		500		
1.4001		-lout = .5	00 A		02		600		
			L,R		02		1200		
		-l _{OUT} = .25	50 A to .500 A,	4,5,6	01		200		
-V _{OUT}		+l _{OUT} = .5	00 A		02		600	1	
			L,R		02		1200		
-V _{OUT}		-IOUT = .50	00 A to .250 A, 000 A	4,5,6	01		500		
1001		+ ¹ OUT = .5	OU A		02		600		
			L,R		02		1200		

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-91614
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL E	SHEET 7

	TABLE	I. Electrical pe	rformance cha	racteristics - Co	ontinued.			
Test	Symbol		ons <u>1</u> / _C ≤+125°C	Group A subgroups	Device Type	Lir	mits	Unit
		-55°C ≤ T ₍ V _{IN} = 28V dc no external sy unless otherw	± 5 percent, rnc, $C_L = 0$, rise specified			Min	Мах	
Output response to transient step line	VOTLINE	$V_{\text{IN}} = 16 \text{ V to}$ $V_{\text{OUT}} = \pm .500$		4,5,6	01,02	-750	+750	mV pk
changes <u>8</u> / <u>9</u> /			L,R]	02	-1500	+1500	
	V _{IN} = 40 \ I _{OUT} = ±.	$V_{IN} = 40 \text{ V to} $ $I_{OUT} = \pm .500$	16 V dc, A		01,02	-750	+750	
			L,R		02	-1500	+1500	
Recovery time to transient step line changes 8/9/	TT _{LINE} $V_{IN} = 16 \text{ V t}$ $I_{OUT} = \pm .50$		40 V dc, A	4,5,6	01,02		1.2	ms
			L,R		02		2.4	•
		V _{IN} = 40 V to I _{OUT} = ±.500	16 V dc,		01,02		1.2	
			L,R		02		2.4	
Turn-on delay <u>10</u> /	TonD	$V_{IN} = 0 \text{ to } 40$ $I_{OUT} = \pm .500$	V dc, A	4,5,6	01,02		25	ms
			L,R		02		50	
Turn-on overshoot 8/	VtonOS	I _{OUT} = ±.500	Α	4	01,02		500	mV pk
		:		5,6	01,02		750	
			L,R	4,5,6	02		1500	
Load fault recovery	TrLF	I _{OUT} = ±.500	A	4,5,6	01,02		50	ms
Z/ <u>8</u> /		L,R		4,5,6	02		100	
Capacitive load, 8/ 11/ (both outputs)	С	No effect on o	ic	4	01,02		10	μf
			L,R	4	02		10	

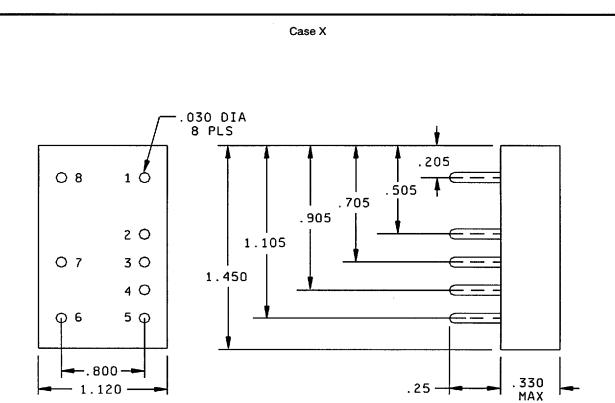
See footnotes at top of next page.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-91614
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		E	8

TABLE I. Electrical performance characteristics.

- 1/ Post irradiation testing shall be in accordance with 4.3.5. herein.
- 2/ For device type 01 the total output power available is 90 percent from either output up to 13.5 W, providing the opposite output is simultaneously carrying 10 percent of the total output power. For device type 02 the total output power available is 70 percent from either output up to 10.5 W providing the opposite output is simultaneously carrying 30 percent of the total output power. Each output must carry a minimum of 10 percent of the total output power in order to maintain regulation on the negative output.
- 3/ Bandwidth guaranteed by design. Tested for 10 kHz to 2 MHz.
- 4/ Cross regulation is the percent change in the measured -V_{OUT} relative to the magnitude of -V_{OUT} when the loads are equal and at full load, ±7.5 W.
- 5/ A TTL level waveform (V_{IH} = 4.5 V minimum, V_{IL} = .8 V maximum) with a 50 percent ±10 percent duty cycle applied to the sync input pin (pin 5) within the sync range frequency shall cause the converters switching frequency to become synchronous with the frequency applied to the sync input pin (pin 5).
- 6/ Load step transition time is 10 microseconds minimum.
- Place is measured from the initiation of the transient to where V_{OUT} has returned to within ±1 percent of V_{OUT} final value.
- 8/ Parameter shall be tested as part of design characterization and after design or process changes. Therefore, the parameter shall be guaranteed to the limits specified in table I.
- 9/ Input step transition time greater than 10 microseconds.
- 10/ Turn-on delay time measurement is for either a step application of power at the input or the removal of a ground signal from the inhibit pin (pin 1) while power is applied to the input.
- 11/ Capacitive load may be any value from 0 to the maximum limit without compromising dc performance.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-91614
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		E	9



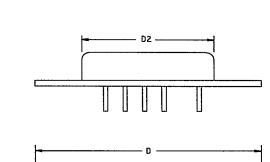
Inches	mm
.030	0.76
.205	5.21
.25	6.4
.330	8.38
.505	12.83
.705	17.91
.800	20.32
.905	22.99
1.105	28.07
1.120	28.45
1.450	36.83

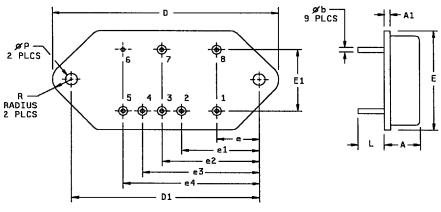
NOTES:

- 1. Dimensions are in inches.
- 2. Metric equivalents are given for general information only.
- 3. Unless otherwise specified, tolerance is ±.01 for two place decimals and ±.005 for three place decimals.
- 4. Device weight: 30 grams maximum.

FIGURE 1. Case outline.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-91614
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		E	10





Case Z

Symbol	Millimete	rs	Inches	
	Min	Max	Min	Max
Α		8.38		.330
A1	.94	1.45	.037	.057
фЬ	.64	.89	.025	.035
D		50.80		2.000
D1	43.82	44.07	1.725	1.735
D2		36.83		1.450
е	8.64	8.89	.340	.350
e1	16.26	16.51	.640	.650
e2	21.37	21.59	.840	.850
.e3	26.41	26.67	1.040	1.050
e4	31.50	31.75	1.240	1.250
E		28.70		1.130
E1	20.07	20.57	.790	.810
L	6.10	6.60	.240	.260
фр	3.20	3.30	.126	.130
R	3.18	3.43	.125	135

- Notes:
 1. The case outline Z was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound shall take precedence.
 2. Device weight: 30 grams maximum

FIGURE 1. Case outline - Continued

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-91614
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		E	11

Device types	01 and 02
Case outlines	X and Z
Terminal number	Terminal symbol
1	Inhibit
2	Positive output
3	Output return
4	Negative output
5	Sync input
6	Case ground
7	Input retum
8	Input

FIGURE 2. Terminal connections.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-91614
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		E	12

TABLE II. Electrical test requirements.

MIL-PRF-38534 test requirements	Subgroups (in accordance with MIL-PRF-38534, group A test table)
Interim electrical parameters	
Final electrical parameters	1*, 2, 3, 4, 5, 6
Group A test requirements	1, 2, 3, 4, 5, 6
Group C end-point electrical parameters	1
Post irradiation end-point electrical parameters for RHA devices	1, 2, 3, 4 ,5, 6

^{*} PDA applies to subgroup 1.

- 4.2 Screening. Screening shall be in accordance with MIL-PRF-38534. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) T_C as specified in accordance with table I of method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 <u>Conformance and periodic inspections</u>. Conformance inspection (CI) and periodic inspection (PI) shall be in accordance with MIL-PRF-38534 and as specified herein.
 - 4.3.1 Group A inspection (CI). Group A inspection shall be in accordance with MIL-PRF-38534 and as follows:
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7, 8, 9, 10, and 11 shall be omitted.
 - 4.3.2 Group B inspection (PI). Group B inspection shall be in accordance with MIL-PRF-38534.
 - 4.3.3 Group C inspection (PI). Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) T_C as specified in accordance with table I of method 1005 of MIL-STD-883.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-91614
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		E	13

- 4.3.4 Group D inspection (PI). Group D inspection shall be in accordance with MIL-PRF-38534.
- 4.3.5 <u>Radiation Hardness Assurance (RHA)</u>. RHA qualification is required only for those devices with the RHA designator as specified herein.

	RHA level L	RHA level R	Units
Total ionizing dose tolerance level	50	100	kRad(Si)
Single event upset survival level (LET)	No guarantee	40	MeV

- a. The manufacturer shall perform a worst-case and radiation susceptibility analysis on the device. This analysis shall show that the minimum performance requirements of each component has adequate design margin under worst-case operating conditions (extremes of line voltage, temperatures, load, frequency, radiation environment, etc.). This analysis guarantees the post-irradiation parameter limits specified in table I.
- b. RHA testing shall be performed at the component level for initial device qualification, and after design changes that may affect the RHA performance of the device. As an alternative to testing, components may be procured to manufacturer radiation guarantees that meet the minimum performance requirements. Component radiation performance guarantees shall be established in compliance with MIL-PRF-19500, Group D or MIL-PRF-38535, Group E, as applicable. For components with less than adequate performance margin, component lot radiation acceptance screening shall be performed.
- c. The manufacturer shall establish procedures controlling component radiation testing, and shall establish radiation test plans used to implement component lot qualification during procurement. Test plans and test reports shall be filed and controlled in accordance with the manufacturer's configuration management system.
- d. The device manufacturer shall designate a RHA program manager to oversee component lot qualification, and to monitor design changes for continued compliance to RHA requirements.
- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.
- 6. NOTES
- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-7603.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0512.
- 6.6 <u>Sources of supply</u>. Sources of supply are listed in QML-38534. The vendors listed in QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DSCC-VA and have agreed to this drawing.

STANDARD
MICROCIRCUIT DRAWING
DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43216-5000

SIZE

A

5962-91614

REVISION LEVEL
E

SHEET
14

STANDARD MICROCIRCUIT DRAWING SOURCE APPROVAL BULLETIN

DATE: 98-02-03

Approved sources of supply for SMD 5962-91614 are listed below for immediate acquisition only and shall be added to QML-38534 during the next revision. QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of QML-38534.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN 1/	number	PIN <u>2</u> /
5962-9161401HXA	50821	MHF+2815D/883
5962-9161401HXC	50821	MHF+2815D/883
5962-9161401HZA	50821	MHF+2815DF/883
5962-9161401HZC	50821	MHF+2815DF/883
5962-9161402HXA	50821	SMHF+2815D/HO
5962-9161402HXC	50821	SMHF+2815D/HO
5962-9161402HZA	50821	SMHF+2815DF/HO
5962-9161402HZC	50821	SMHF+2815DF/HO
5962L9161402HXA	50821	SMHF+2815D/HL
5962L9161402HXC	50821	SMHF+2815D/HL
5962L9161402HZA	50821	SMHF+2815DF/HL
5962L9161402HZC	50821	SMHF+2815DF/HL
5962R9161402HXA	50821	SMHF+2815D/HR
5962R9161402HXC	50821	SMHF+2815D/HR
5962R9161402HZA	50821	SMHF+2815DF/HR
5962R9161402HZC	50821	SMHF+2815DF/HR
5962L9161402KXA	50821	SMHF+2815D/KL
5962L9161402KXC	50821	SMHF+2815D/KL
5962L9161402KZA	50821	SMHF+2815DF/KL
5962L9161402KZC	50821	SMHF+2815DF/KL
5962R9161402KXA 5962R9161402KXC 5962R9161402KZA 5962R9161402KZC	50821 50821 50821 50821 50821	SMHF+2815D/KR SMHF+2815D/KR SMHF+2815DF/KR SMHF+2815DF/KR

^{1/} The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not specified contact the vendor to determine its availability.

availability.

2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

50821

Vendor name and address

Interpoint Corporation 10301 Willows Road Redmond, WA 98052

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.